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Diamond wire for slicing

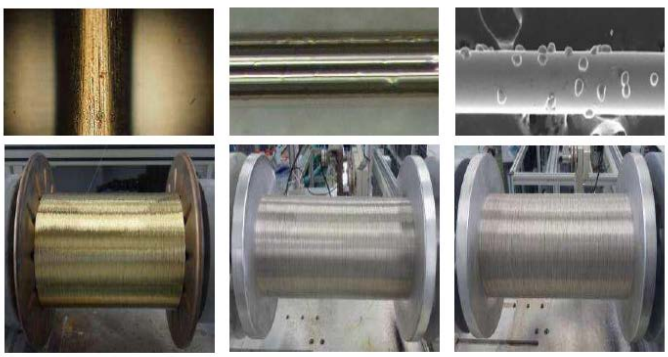
SUNTEK Diamond wire is used for cutting silicon (mono and multi crystalline), sapphire, optics and other hard-brittle material, with better efficient and performance.

Wire Dia.	Application	Core wire	Diamond grit	Tolerance	Break Tension	Diamond Density
mm		mm	um	±mm	N	pcs/mm
0.12	Silicon slicing	0.1	10-20	0.002	30	40-60
0.14		0.12			40	
0.25	Sapphire slicing	0.18	30-40	0.01	75	20-30
0.29		0.22			140	
0.31	Filament cutting	0.22	30-40	0.01	140	70-90
0.35	Silicon bricking	0.25	40-50	0.02	160	30-40
0.35		0.25			150	
0.37		0.27			190	
0.42	Optics cutting	0.32	40-50	0.02	230	30-40
0.5		0.35			250	

Wire diameter from 0.12 to 0.55.

Diamond wire strength is 220% of steel wire

One spool can be 2 Kilo to 50 kilo



Core wire → Pretreatment → Diamond wire

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